

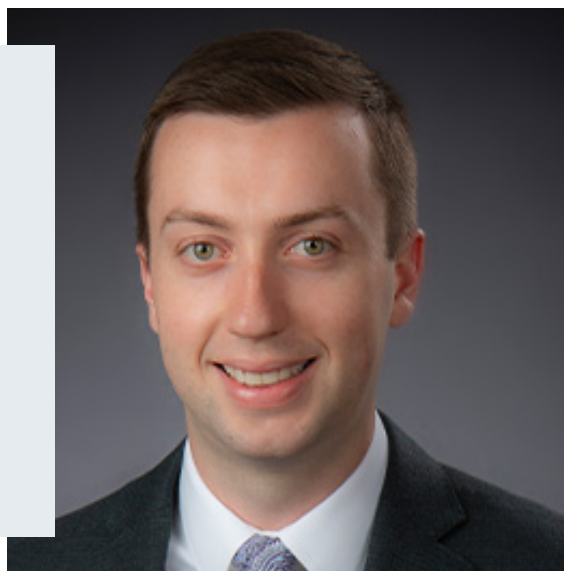
William C. Paltz

Associate

wpaltz@foley.com

Dallas

214.999.4026



William (Will) Paltz focuses his practice on preparing and prosecuting domestic and international patent applications across a broad spectrum of technology areas, including data science and predictive analytics, advanced computer modeling and artificial intelligence/machine learning, advertisements and marketing, financial technologies, and business methods.

Will assists clients by proactively navigating and alleviating Section 101 issues even before filing. His strategic approach involves crafting compelling application strategies aimed at securing favorable reviews from the U.S. Patent and Trademark Office. Additionally, he demonstrates specialized competence in managing the intricacies of 3600 art unit applications linked to software and business method inventions.

Before joining Foley, Will was a control hardware engineer intern at Rockwell Automation, where he was responsible for field-programmable gate array (FPGA) design and development activities. He also was a software and firmware quality engineer intern at Rockwell Automation, where he contributed to a variety of projects, including backend development and software and firmware development lifecycle optimization.

Will currently attends Southern Methodist University Dedman School of Law and anticipates completing his degree in 2023.

Affiliations

- Member, Institute of Electrical and Electronics Engineers (IEEE)

Practice Areas

- [Intellectual Property](#)
- [Mechanical & Electromechanical Technologies](#)

Education



FOLEY & LARDNER LLP

- University of Wisconsin-Milwaukee (B.S., summa cum laude, 2019)
 - Dean's list, College of Engineering & Applied Science (2015-2019)
 - Computer Engineering

Admissions

- U.S. Patent and Trademark Office